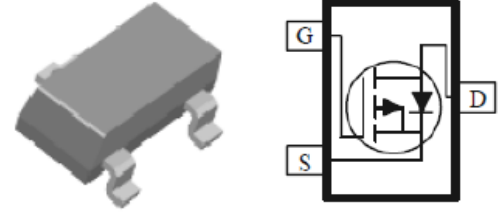




MS23P21 P-Channel 20-V (D-S) MOSFET

GENERAL DESCRIPTION

These miniature surface mount MOSFETs utilize a high cell density trench process to provide low RDS(on) and to ensure minimal power loss and heat dissipation. Typical applications are DC-DC converters and power management in portable and battery-powered products such as computers, printers, and PCMCIA cards, cellular and cordless telephones.



FEATURES

- Low rDS(on) provides higher efficiency and extends battery life
- Low thermal impedance copper leadframe SOT-23 saves board space
- Fast switching speed
- High performance trench technology

1. Gate 2. Drain 3. Source
RoHS
COMPLIANT

HALOGEN
FREE
Available

Absolute Maximum Ratings (Tc=25°C unless otherwise noted)

| Parameter | Symbol | Value | Unit |
|--|----------|----------|------|
| Drain-Source Voltage | VDS | -20 | V |
| Gate-Source Voltage | VGS | ±8 | V |
| Continuous Drain Current @ TC=25°C | ID | -4.1 | A |
| Pulsed Drain Current | IDM | -10 | A |
| Continuous Source Current (Diode Conduction) | IS | 0.46 | A |
| Operating Junction and Storage Temperature | Tj, Tstg | -55~+150 | °C |
| Power Dissipation @ TC=25°C | Pd | 1.25 | W |

NOTE:

1. Repetitive rating; pulse width limited by maximum junction temperature.

Thermal characteristics (Tc=25°C unless otherwise noted)

| Parameter | Symbol | Value | Unit |
|-----------------------------|--------|-------|------|
| Maximum Junction-to-Ambient | RθJA | 100 | °C/W |
| Maximum Junction-to-Case | RθJc | 150 | |



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| SPECIFICATIONS ($T_A = 25^\circ\text{C}$ UNLESS OTHERWISE NOTED) | | | | | | |
|---|--------------|--|--------|-------|-----------|------|
| Parameter | Symbol | Test Conditions | Limits | | | Unit |
| | | | Min | Typ | Max | |
| Static | | | | | | |
| Gate-Threshold Voltage | $V_{GS(th)}$ | $V_{DS} = V_{GS}, I_D = -250 \mu\text{A}$ | -0.4 | | -1.5 | V |
| Gate-Body Leakage | I_{GSS} | $V_{DS} = 0 \text{ V}, V_{GS} = \pm 8 \text{ V}$ | | | ± 100 | nA |
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{DS} = -16 \text{ V}, V_{GS} = 0 \text{ V}$ | | | -1 | uA |
| | | $V_{DS} = -16 \text{ V}, V_{GS} = 0 \text{ V}, T_J = 55^\circ\text{C}$ | | | -10 | |
| On-State Drain Current ^A | $I_{D(on)}$ | $V_{DS} = -5 \text{ V}, V_{GS} = -4.5 \text{ V}$ | -5 | | | A |
| Drain-Source On-Resistance ^A | $r_{DS(on)}$ | $V_{GS} = -4.5 \text{ V}, I_D = -4.1 \text{ A}$ | | | 79 | mΩ |
| | | $V_{GS} = -2.5 \text{ V}, I_D = -3.2 \text{ A}$ | | | 110 | |
| Forward Transconductance ^A | g_{fs} | $V_{DS} = -5 \text{ V}, I_D = -1.25 \text{ A}$ | | 9 | | S |
| Diode Forward Voltage | V_{SD} | $I_S = -0.46 \text{ A}, V_{GS} = 0 \text{ V}$ | | -0.65 | | V |
| Pulsed Body-Diode Current ^C | I_{SM} | | | | -10 | A |
| Dynamic^b | | | | | | |
| Total Gate Charge | Q_g | $V_{DS} = -10 \text{ V}, V_{GS} = -4.5 \text{ V}, I_D = -4.1 \text{ A}$ | | 7.2 | | nC |
| Gate-Source Charge | Q_{gs} | | | 1.7 | | |
| Gate-Drain Charge | Q_{gd} | | | 1.5 | | |
| Input Capacitance | C_{iss} | P-Channel $V_{DS} = -15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$ | | 500 | | pF |
| Output Capacitance | C_{oss} | | | 90 | | |
| Reverse Transfer Capacitance | C_{rss} | | | 60 | | |
| Turn-On Delay Time | $t_{d(on)}$ | $V_{DD} = -10 \text{ V}, I_L = -1 \text{ A}, V_{GEN} = -4.5 \text{ V}, R_G = 6 \Omega$ | | 10 | | ns |
| Rise Time | t_r | | | 9 | | |
| Turn-Off Delay Time | $t_{d(off)}$ | | | 27 | | |
| Fall-Time | t_f | | | 11 | | |

Notes

- a. Pulse test: PW ≤ 300us duty cycle ≤ 2%.
- b. Guaranteed by design, not subject to production testing.
- c. Repetitive rating, pulse width limited by junction temperature.